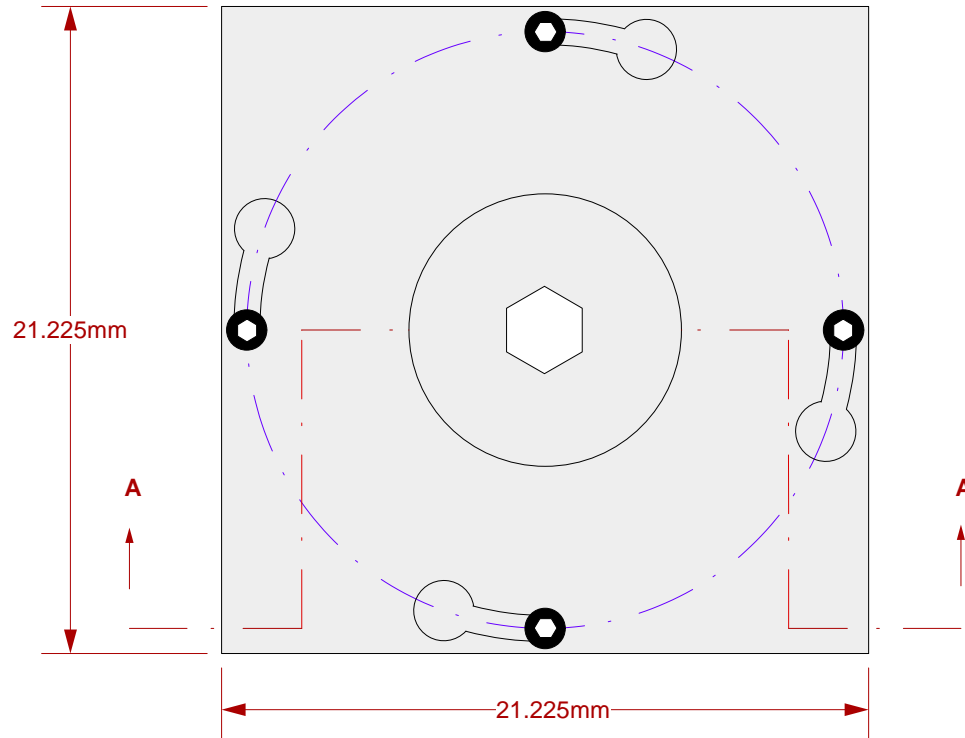
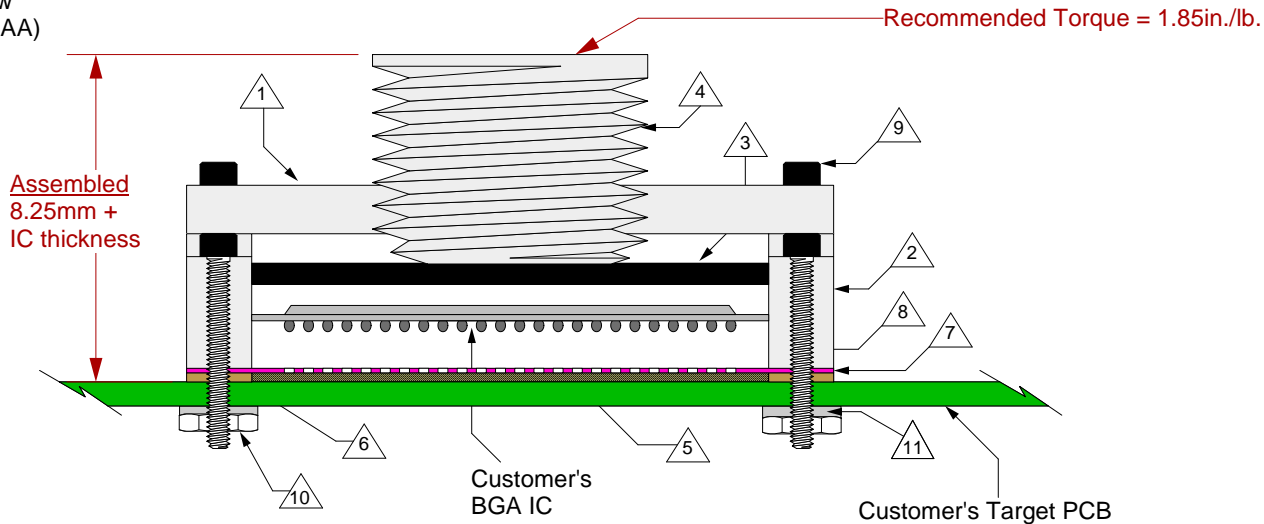


Top View



Side View
(Section AA)




GHz BGA Socket - Direct mount, solderless

Features

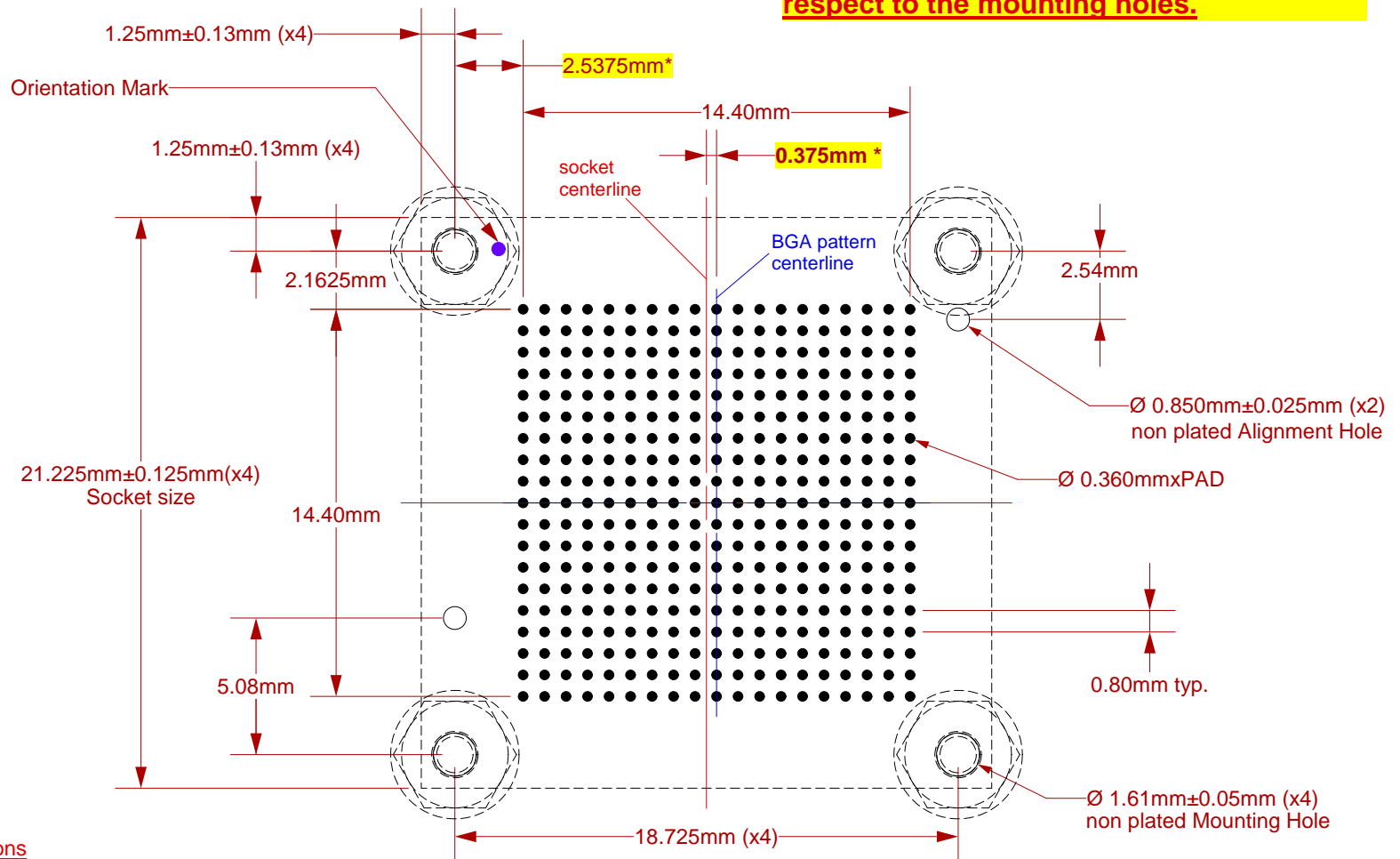
- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

- 1 Socket Lid: Black anodized Aluminum.
Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum.
Thickness = 5mm.
- 3 Compression Plate: Black anodized Aluminum.
Thickness = 2.5mm.
- 4 Compression screw: Clear anodized Aluminum.
Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle).
Thickness = 0.75mm.
- 6 Elastomer Guide: Non-clad FR4.
Thickness = 0.725mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread , 9.525mm long.
- 9 Socket lid screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread , 4.76mm long.
- 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- 11 Nylon washer: 1.73mm ID; 4.78mm OD, 0.64mm thick

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		Drawing: Umer Qureshi		Date: 08/02/10
		File: SG-BGA-6269 Dwg.mcd		Modified:

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

Note: BGA pattern is not symmetrical with respect to the mounting holes. It is offset by 0.375mm to the right of center with respect to the mounting holes.




Target PCB Recommendations

Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

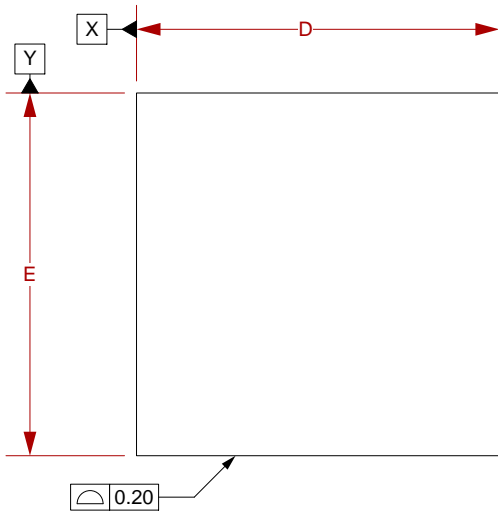
NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.

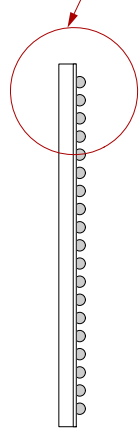
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		File: SG-BGA-6269 Dwg.mcd	Modified:	

Compatible BGA Spec

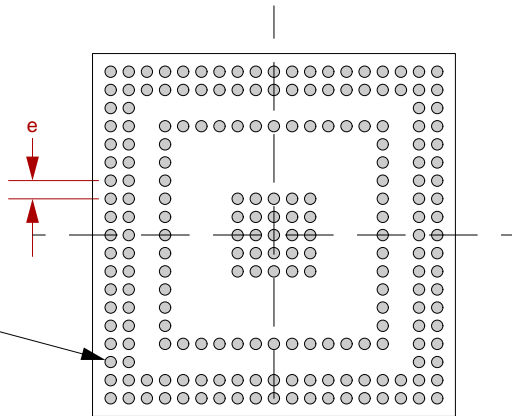
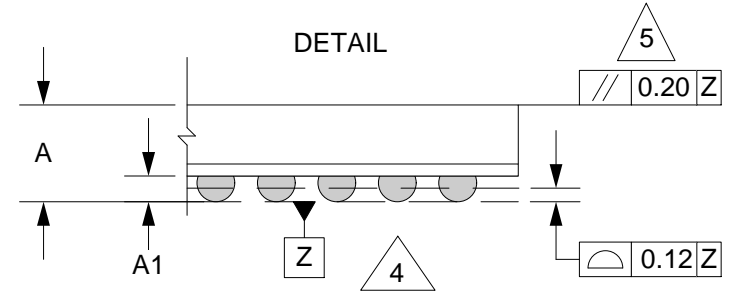
TOP VIEW



SIDE VIEW



DETAIL



BOTTOM VIEW

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.7
A1	0.27	
b	0.45	0.55
D	15.85	16.15
E	15.85	16.15
e	0.8 BSC	

Array: 19x19

SG-BGA-6269 Drawing

Status: Released

Scale: NA

Rev: A



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